SDAS055E - APRIL 1982 - REVISED JULY 1996

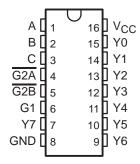
- Designed Specifically for High-Speed Memory Decoders and Data Transmission Systems
- Incorporate Three Enable Inputs to Simplify Cascading and/or Data Reception
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

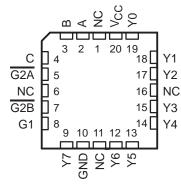
The 'ALS138A and 'AS138 are 3-line to 8-line decoders/demultiplexers designed for highperformance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance systems, these devices can be used to minimize the effects of decoding. When employed system high-speed memories with a fast enable circuit, the delay times of the decoder and the enable time of the memory are usually less than the typical access time of the memory. The effective system delay introduced by the Schottky-clamped system decoder is negligible.

The conditions at the binary-select (A, B, and C) inputs and the three enable (G1, G2A, and G2B) inputs select one of eight output lines. Two active-low and one active-high enable inputs

SN54ALS138A, SN54AS138 . . . J PACKAGE SN74ALS138A, SN74AS138 . . . D OR N PACKAGE (TOP VIEW)



SN54ALS138A, SN54AS138 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

The SN54ALS138A and SN54AS138 are characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS138A and SN74AS138 are characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

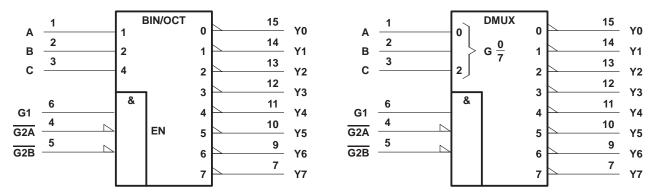


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FUNCTION TABLE

		INP	UTS						OUT	PUTS			
	ENABLE	E		SELECT	ī				0011	7013			
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Н	Х	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
Х	X	Н	Х	Χ	Χ	Н	Н	Н	Н	Н	Н	Н	Н
L	X	X	Х	Χ	Χ	Н	Н	Н	Н	Н	Н	Н	Н
Н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
Н	L	L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н
Н	L	L	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н
Н	L	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
Н	L	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н
Н	L	L	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н
Н	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н
Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L

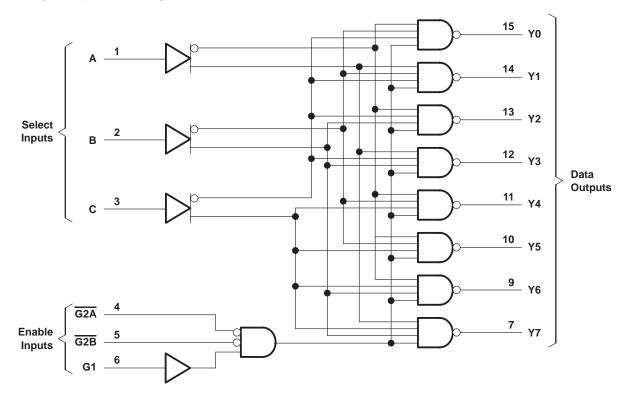
logic symbols (alternatives)†



[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.



logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

recommended operating conditions

		SNS	4ALS13	8A	SN7	'4ALS13	8A	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
loh	High-level output current			-0.4			-0.4	mA
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST C	TEST CONDITIONS			8A	SN7	'4ALS13	8A	UNIT
PARAMETER	TEST CONDITIONS			TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT
VIK	V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
Voн	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
\/o.	V _{CC} = 4.5 V	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
VOL	VCC = 4.5 V	I _{OL} = 8 mA					0.35	0.5	V
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
lін	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
ΙΟ§	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-20		-112	-30		-112	mA
Icc	V _{CC} = 5.5 V			5	10		5	10	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL:	C = 4.5 V = 50 pF, = 500 Ω, = MIN to	to 5.5 V,		UNIT
	, ,	, , ,	SN54AL	S138A	SN74ALS138A		
			MIN	MAX	MIN	MAX	
t _{PLH}	A, B, C	Any Y	2	28	5	22	ns
t _{PHL}	А, Б, С	Ally f	6	22	6	18	115
t _{PLH}	G or \overline{G}	Any Y	2	22	3	17	ns
t _{PHL}	G or G	Ally I	4	21	4	17	115

[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 \
Input voltage, V _I	7 \
Operating free-air temperature range, T _A : SN54AS138	
SN74AS138	0°C to 70°C
Storage temperature range, T _{stg}	−65°C to 150°C

recommended operating conditions

		SI	N54AS13	8	SI	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-2			-2	mA
loL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST C	TEST CONDITIONS					N74AS13	8	UNIT
PARAMETER	TEST C	TEST CONDITIONS				MIN	TYP [‡]	MAX	UNII
VIK	V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		VCC -2	2		V
VoL	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.35	0.5		0.35	0.5	V
lį	$V_{CC} = 5.5 V$,	V _I = 7 V			0.1			0.1	mA
lН	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
IIL	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.5			-0.5	mA
ΙΟ [§]	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
ICCH	V _{CC} = 5.5 V			12	17.5		12	17.5	mA
ICCL	V _{CC} = 5.5 V			14	20		14	20	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

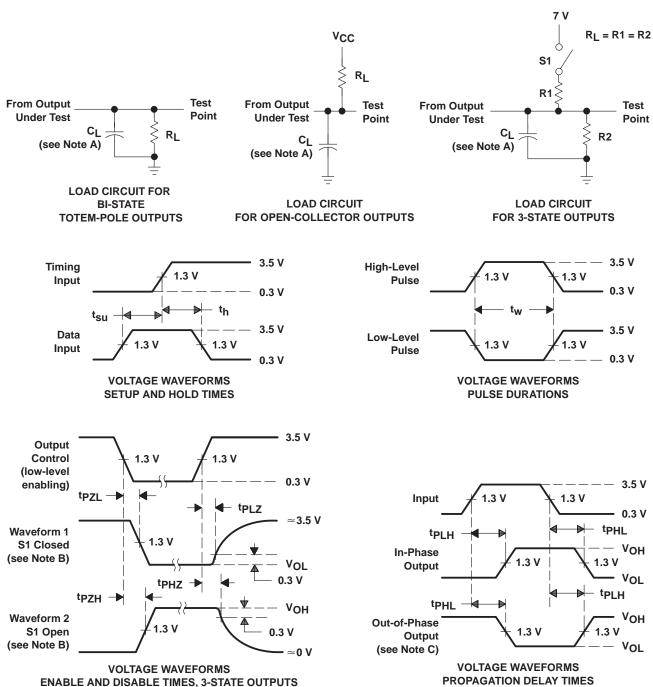
SDAS055E - APRIL 1982 - REVISED JULY 1996

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L R _L	= 50 pF = 500 £		V,	UNIT
	, ,	, , ,	SN54A	\S138	SN74A	S138	
			MIN	MAX	MIN	MAX	
t _{PLH}	A, B, C	Any Y	2	11	2	10	ns
t _{PHL}	А, Б, С	Ally I	2	11	2	9.5	115
tPLH	G1	Any V	2	11.5	2	10	ns
^t PHL	91	Any Y	2	11	2	10	115
t _{PLH}	G 2	Any V	2	9	2	7.5	nc
t _{PHL}	G2	Any Y	2	10	2	8.5	ns

T For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
5962-86866012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	-55 to 125	5962- 86866012A SNJ54ALS 138AFK	Samples
5962-8686601FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	-55 to 125	5962-8686601FA SNJ54ALS138AW	Samples
JM38510/37701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37701B2A	Samples
JM38510/37701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37701BEA	Samples
M38510/37701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type		JM38510/ 37701B2A	Samples
M38510/37701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37701BEA	Samples
SN54ALS138AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS138AJ	Sample
SN54AS138J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS138J	Sample
SN74ALS138AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS138A	Sample
SN74ALS138ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS138A	Sample
SN74ALS138ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS138A	Sample
SN74ALS138ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS138A	Sample
SN74ALS138ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS138A	Sample
SN74ALS138ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS138A	Sample
SN74ALS138AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS138AN	Sample
SN74ALS138ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS138AN	Sample



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
SN74ALS138ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS138A	Samples
SN74ALS138ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS138A	Samples
SN74ALS138ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS138A	Samples
SN74AS138D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS138	Samples
SN74AS138DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS138	Samples
SN74AS138DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS138	Samples
SN74AS138DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS138	Samples
SN74AS138DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS138	Samples
SN74AS138DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS138	Samples
SN74AS138N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS138N	Samples
SN74AS138N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74AS138NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS138N	Samples
SN74AS138NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS138	Samples
SN74AS138NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS138	Samples
SN74AS138NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS138	Sample
SNJ54ALS138AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86866012A SNJ54ALS 138AFK	Sample
SNJ54ALS138AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54ALS138AJ	Sample
SNJ54ALS138AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8686601FA SNJ54ALS138AW	Sample



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PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
SNJ54AS138FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type		SNJ54AS 138FK	Samples
SNJ54AS138J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS138J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF SN54ALS138A, SN54AS138, SN74ALS138A, SN74AS138:

Catalog: SN74ALS138A, SN74AS138

Military: SN54ALS138A, SN54AS138





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NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All ulmensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS138ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS138ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS138DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AS138NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS138ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS138ANSR	SO	NS	16	2000	367.0	367.0	38.0
SN74AS138DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AS138NSR	SO	NS	16	2000	367.0	367.0	38.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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